

VERSION SHOWING THE CHANGES TO THE SPECIFICATION

IN THE SPECIFICATION:

Amend the specification as follows:

Page 1, line 1:

Description

Paragraph [0014] of the published application:

Figure 1 shows a carrier substrate (for example a PET film) indicated at 1 with the corresponding lower conductor tracks 2 (for example gold, polyaniline, PEDOT, carbon black, graphite and conducting silver). The component comprises a plastic substrate which includes one of the following materials: PET, PP (polypropylene), PEN, polyimide, polyamide and coated paper.

Paragraph [0018] of the published application

Figure 5 shows the same layer structure as that shown in Figures 1 -3, except that in Figure 5 the two functional layers 4[[, 5]] are restricted to one layer 4.

Paragraph [0020] of the published application:

[0020] In Figure 7₁ the two structures have been brought into contact with each other, as occurs₁ for example₁ in a lamination process. As a result₁ both the respective functional layers 4[[, 5]] and the respective vias form a unit and produce the defined electrical connection. The shape of the through-plating 3₁ which results in that case₁ and which can be recognized ~~recognised~~ in the cross-sectional profile as is here a hyperboloid, that is to say₁ the shape of two truncated cones ~~which~~ are joined 'head-to-

head'.

Paragraphs [0021], [0022] and [0023] of the published application:

[0021] Figure 8 shows another way of producing the through-plating. A defined disruption location 7 has been applied to the lower conductor track 2. The disruption location 7 can comprise both conductive and also insulating material. In addition the disruption location 7 can be produced by a local chemical or physical treatment. The through-plating 3 is shaped by tearing open the functional layer or layers 4 at the disruption location 7 and subsequently filling the region around the disruption location 7 with conductive material of the upper conductor track 6.

[0022]The disruption location 7 provides that, around it, the subsequently applied central functional layer or layers 4, 5 tears or tear open and/or is or are absent due to non-wetting or in some other fashion, so that a region is produced around the disruption location 7, in which the lower layer 2 to be contacted is exposed, in the operation of forming the upper layer 6 to be contacted.

[0023]The contacting of the conducting layer 2 to the conducting layer 6 functions by virtue of the exposed region on the layer 2 being larger than the disruption location 7. For that reason the disruption location 7 can comprise both conducting and also insulating material.